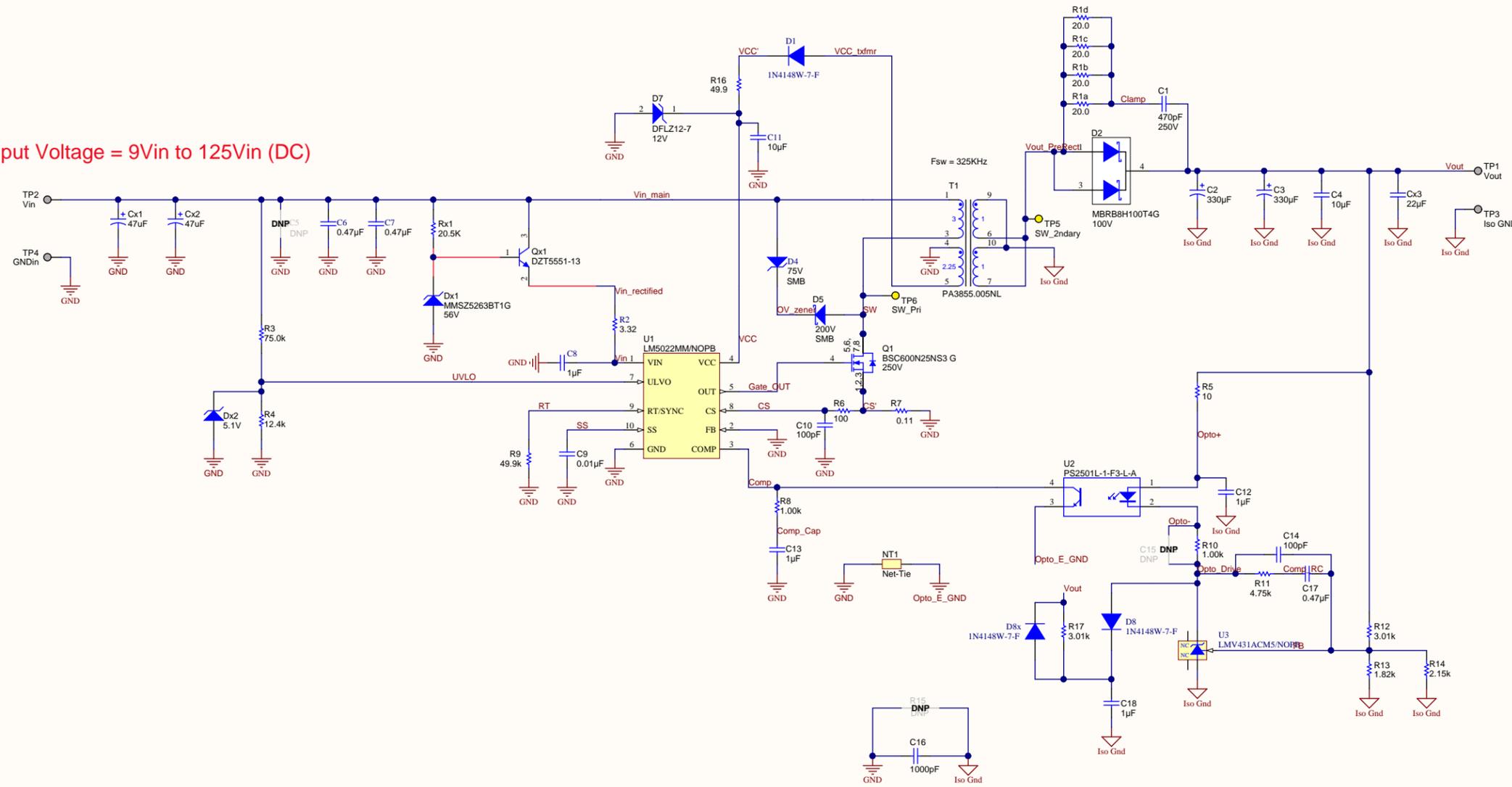


Input Voltage = 9Vin to 125Vin (DC)

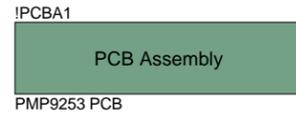
5Vout @ 3A Max.



***NOTES:**

1. All components containing an "x" suffix were added to the design after the PCB was fabricated. These components to not have placeholders on the PCB.
2. R1a, R1b, R1c, and R1d can be replaced by a single 5 ohm resistor rated at 1W or higher.
3. RED traces on the schematic signify wiring that was performed as a modification to the original PCB layout. Traces do not exist on the PCB for these nets.
4. Design is built on PMP9253 PCB.

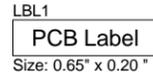
| | | |
|--|---|----------|
| Title | | |
| LM5022 Wide Vin Isolated Flyback Converter | | |
| Size | Number | Revision |
| C | PMP20127 | |
| Date: | 12/4/2017 | Sheet of |
| File: | C:\Users\...PMP20127 Schematic.SchDoc Drawn By: | |



PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

PCB
LOGO
FCC disclaimer



| Variant/Label Table | |
|---------------------|------------|
| Variant | Label Text |
| 001 | |
| | |
| | |
| | |
| | |
| | |
| | |

| | | |
|---|---|---|
| Orderable: ChangeMe! | Designed for: | Mod. Date: 3/18/2016 |
| TID #: PMP20127 | Project Title: LM5022 Wide Vin Isolated Flyback | |
| Number: PMP20127 | Rev: A | Sheet Title: Hardware |
| SVN Rev: Version control disabled | Assembly Variant: 001 | Sheet: 2 of 2 |
| Drawn By: | File: PMP20127_EVM_Hardware.SchDoc | Size: B |
| Engineer: Hrag Kasparian | Contact: http://www.ti.com/support | http://www.ti.com |

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